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LM(2)5017/8/9 Universal Board

Quantity	Designator	Value	Description	Package	PartNumber	Manufacturer
1	C1	2.2uF	CAP, CERM, 2.2uF, 25V, +/-10%, X7R, 0805	0805	Std	Std
1	C3	1uF	CAP, CERM, 1uF, 10V, +/-10%, X5R, 0402	0402	Std	Std
1	C5	3300pF	CAP, CERM, 3300pF, 50V, +/-10%, X7R, 0402	0402	Std	Std
1	R1	see schematic	RES, 1%, 0.063W, 0402	0402	Std	Std
1	C2	0.01uF	CAP, CERM, 0.01uF, 16V, +/-10%, X5R, 0402	0402	Std	Std
1	C4	0.1uF	CAP, CERM, 0.1uF, 10V, +/-10%, X7R, 0402	0402	Std	Std
1	C6	4.7uF	CAP, CERM, 4.7uF, 10V, +/-10%, X5R, 0603	0603	Std	Std
1	J1	1x3	Header, TH, 100mil, 1x3, Gold plated, 230 mil above insulator	90121-0123	90121-0123	Molex
1	L1	33uH	Inductor, SMD, 33uH, 0.5A, 0.382 ohm	WE-TPC-M2	744042330	Wurth Elektronik
1	R2	22.1k	RES, 22.1k ohm, 1%, 0.063W, 0402	0402	Std	Std
1	R3	10.0k	RES, 10.0k ohm, 1%, 0.063W, 0402	0402	Std	Std
1	R4	see schematic	RES, 1%, 0.063W, 0402	0402	Std	Std
1	U1	LM5017SD	IC, 100 V, 600 mA Constant On-Time Synchronous Buck	LLP-8	LM5017SD	Texas Instruments

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